

# 3.0V to 5.5V RS485/RS422 Transceiver with ±15kV ESD Protection

## 1. Features

# High-Performance and Compliant with RS-485 EIA/ TIA-485 Standard

- High-Speed Data Rates: 20Mbps
- 1/8 Unit Load Enables up to 256 Nodes on the Same Rus

## • Integrated Protection for Robust Communication

- ±30V Fault Protection Range on Driver Outputs/Receiver Inputs
- ±15V Common-Mode Voltage Range
- ±15kV Human Body Model ESD Protection on the Bus Lines
- Hot-Swap Input Eliminates False Transitions during Power-up or Power-down
- Short-Circuit Protection
- Thermal Shutdown
- True Fail-Safe Guarantees Known Receiver Output State

## Low Power

- 960μA (max.) @ Receive Mode
- Shutdown Current < 5µA
- 3.0V to 5.5V Supply Voltage Range
- Wide Operating Temperature Range: -40°C to 125°C
- 14 pin SOIC Package

## 2. Applications

- Motor Driver
- Industrial Automation and Control
- Power Grid Infrastructure
- Building Automation
- HVAC System
- Video Surveillance
- Process Control
- Wireless Infrastructure

# 3. Description

The CA-IF4220NF is low-power, full-duplex transceiver for RS-485/RS-422 communications in harsh environments. This device features ±30V fault protection for overvoltage conditions on the bus lines that ensure robust protection for the communication interface. It also has ±15V wide common-mode range (CMR), this feature was specifically

designed for systems where there is a large common-mode voltage present due to either nearby electrically noisy equipment or large ground differences due to different grounds or long-distance transmission. The bus pins are protected against ±15kV electro-static discharge (ESD) shocks, eliminating the need for additional system level protection components.

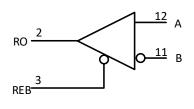
The CA-IF4220NF contains one driver (TX) and one receiver (RX), operates over the +3.0V to +5.5V supply range, making it convenient for designers to use one part with either +3.3V or +5.0V supply systems. The CA-IF4220NF can transmit and receive at data rate up to 20Mbps. It also includes fail-safe circuitry, guaranteeing a logic-high receiver output when the receiver inputs are shorted or open.

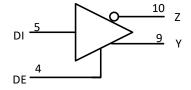
The CA-IF4220NF is specified over the -40°C to +125°C wide operating temperature range and is available in 14-pin SOIC package for industry drop-in compatibility.

## **Device Information**

Part Number	nber Package Package Size (Nom			
CA-IF4220NF	SOIC14	3.9mm x 8.65mm		

# **CA-IF4220NF Simplified Schematic Diagram**







# 4. Ordering Information

**Table 4-1. Ordering Information** 

Part # Full/Half-Duplex		Data Rate (Mbps)	Number of Nodes on Bus	Package	
CA-IF4220NF	Full duplex	20	256	14-pin SOIC	





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# 5. **Revision History**

Revision Number	Description	Page Changed
Version 1.00	N/A	N/A

# 6. Pin Configuration and Descriptions

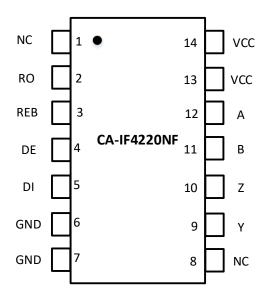


Figure 6-1. CA-IF4220NF pin configuration

Table 6-1. CA-IF4220NF pin description

Pin Name	Pin Number	Description
RO	2	Receiver data output. With REB low, RO is high when $(V_A - V_B) > V_{TH+}$ and is low when $(V_A - V_B) < V_{TH+}$
KO	2	V <sub>TH</sub> RO is high impedance when REB is high.
		Receiver output enable. Drive REB low or connect to GND to enable RO. Drive REB high to
REB	3	disable the receiver and put RO in high impedance. Drive REB high and DE low to force the IC
		into low-power shutdown mode.
DF	4	Driver output enable. Drive DE high to enable the driver. Drive DE low or connect to GND to
DL	7	disable the driver. Drive REB high and DE low to force the IC into low-power shutdown mode.
		Driver data input. With DE high, a logic low on DI forces the noninverting output (Y) low and the
DI	5	inverting output (Z) high; a logic high on DI forces the noninverting output high and the
		inverting output low.
GND	6, 7	Ground.
Υ	9	Noninverting RS-485/RS-422 driver output.
Z	10	Inverting RS-485/RS-422 driver output.
В	11	Inverting RS-485/RS-422 receiver input.
А	12	Noninverting RS-485/RS-422 receiver input.
NC	1, 8	No Connection. Not internally connected.
V <sub>cc</sub>	13, 14	Power supply input. Bypass $V_{CC}$ to GND with at least $0.1\mu F$ capacitor as close to the device as possible.



# 7. Specifications

# 7.1. Absolute Maximum Ratings<sup>1</sup>

	Parameters	Min	Max	Unit
V <sub>CC</sub>	Power supply voltage	-0.3	7.0	V
V <sub>IO</sub>	Voltage at A, B, Z, Y	-30	30	V
V <sub>IO</sub>	Voltage at DI, DE, REB	-0.3	7.0	V
V <sub>IO</sub>	Voltage at RO	-0.3	V <sub>CC</sub> +0.3	V
T <sub>J</sub>	Operating junction temperature		150	°C
T <sub>STG</sub>	Storage temperature range	-65	150	°C

## Note:

# 7.2. ESD Ratings

	Parameters Parameters Parameters		
	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, bus pin <sup>1</sup>	±15	kV
V <sub>ESD</sub> Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, other pin <sup>1</sup>	±6	kV
	Charged device model (CDM), per JEDEC specification JESD22-C101, all pins	±2	kV
	·		

## Notes:

- 1. Per JEDEC document JEP155, 500V HBM allows safe manufacturing of standard ESD control process.
- 2. Per JEDEC document JEP157, 250V CDM allows safe manufacturing of standard ESD control process.

# 7.3. Recommended Operating Conditions

	Parameters	Min	Тур	Max	Unit
V <sub>CC</sub>	Analog power supply	3	5	5.5	V
V <sub>IN</sub>	Input voltage at bus terminal	-15		15	V
V <sub>IL</sub>	Low-level input voltage	0		0.8	V
V <sub>IH</sub>	High-level input voltage	2		V <sub>CC</sub>	V
R <sub>L</sub>	Differential load resistance	54			Ohm
1/t <sub>UI</sub>	Data rate			20	Mbps
T <sub>A</sub>	Ambient temperature	-40		125	°C
TJ	Operating junction temperature	-40		150	°C

# 7.4. Thermal Information

Thermal Metric	CA-IF4220NF SOIC14	Unit
$R_{\theta JA}$ Junction-to-ambient thermal resistance	120	°C/W

<sup>1.</sup> The stresses listed under "Absolute Maximum Ratings" are stress ratings only, not for functional operation condition. Exposure to absolute maximum rating conditions for extended periods may cause permanent damage to the device.



# 7.5. Electrical Characteristics

All typical specs are at VCC = 5V, TA = 25°C, Min/Max specs are over recommended operating conditions unless otherwise specified.

	Parameters	Test Condition	ıs	Min	Тур	Max	Unit
Driver							
		$R_L = 60\Omega$ , $-15V \le V_{test} \le 15V$	/ (See	1.5	_		T ,,
		Figure 8-1) <sub>(1)</sub>	Figure 8-1) <sub>(1)</sub>		3.5		V
Iv. I	Differential autority altern	$R_L = 60\Omega$ , $-15V \le V_{test} \le 15V$	Ι,	2.1			
V <sub>OD</sub>	Differential-output voltage	4.5V≤V <sub>CC</sub> ≤5.5V (See Figu	ure 8-1)	2.1			
		R <sub>L</sub> =100Ω (See Figure 8-2	2)	2	4		V
		R <sub>L</sub> =54Ω (See Figure 8-2)		1.5	3.7		V
Δ V <sub>OD</sub>	Change in differential-output voltage	$R_L$ =54 $\Omega$ (See Figure 8-2)		-200		200	mV
Voc	Common-mode output voltage			1	V <sub>cc</sub> /2	3	V
۸۱/	Change in steady-state common-mode output	K <sub>L</sub> =54Ω (See Figure 8-2)		-200		200	m\/
$\Delta V_{OC(SS)}$	voltage			-200		200	mV
I <sub>OS</sub>	Short-circuit output current	-7V≤V <sub>0</sub> ≤12V		-250		250	mA
Receiver							
		DF-0\/ \/ -0\/ or F\/	V <sub>I</sub> =12V		75	125	uA
1	Bus input current	DE=0V, V <sub>CC</sub> =0V or 5V	V <sub>I</sub> =-7V	-100	-43		uA
I <sub>I</sub>		DE 01/1/ 01/2= E1/	V <sub>I</sub> =15V		91	125	uA
		DE=0V, V <sub>CC</sub> =0V or 5V	V <sub>I</sub> =-15V	-200	-97		uA
V <sub>TH+</sub>	Receiver differential threshold voltage rising		•		-100	-20	mV
V <sub>TH-</sub>	Receiver differential threshold voltage falling	Over common mode range		-200	-130		m۷
V <sub>HYS</sub>	Receiver input hysteresis				30		mV
V <sub>OH</sub>	High-level output voltage	I <sub>OH</sub> =-4mA		V <sub>CC</sub> -0.4	V <sub>CC</sub> -0.2		V
V <sub>OL</sub>	Low-level output voltage	I <sub>OL</sub> =4mA			0.2	0.4	V
I <sub>OZR</sub>	Output high-impedance current	V <sub>O</sub> =0V or V <sub>CC</sub> , REB at V <sub>C</sub>	C	-1		1	uA
Input logic							
VIH	Logic-high input	DI, V <sub>CC</sub> =5.5V		2			V
VIL	Logic-low input	DI, V <sub>CC</sub> =4.5V				0.8	V
I <sub>IN</sub>	Logic input current	3V≤V <sub>CC</sub> ≤5.5V, 0V≤V <sub>IN</sub> ≤V	cc	-6.2		6.2	uA
Device							
		Driver and receiver ena	bled,	0.4	0.0	1.2	
		REB=0V, DE = $V_{CC}$ , no los	ad	0.4	0.8	1.2	mA
		Driver enabled, receive	disabled,		0.8	1.2	mA
i	Supply current (quiescent)	REB= $V_{CC}$ , DE = $V_{CC}$ , no load			0.8	1.2	IIIA
I <sub>CC</sub>	Supply culterit (quiescellt)	Driver disabled, receiver enabled,			700	060	11.0
		REB=0V, DE = 0V, no load			700	960	uA
		Driver disabled, receiver disabled,		d,	2.4	5	uA
		REB= $V_{CC}$ , DE = 0V, D=op	en, no load		۷.4	<u> </u>	
T <sub>SD</sub>	Thermal shutdown temperature				180		$^{\circ}\mathbb{C}$

#### Notes:

- 1.  $|V_{OD}| \ge 1.4 \text{ V}$  with  $T_A > 85^{\circ}\text{C}$ ,  $V_{test} < -7 \text{ V}$  and  $V_{CC} < 3.135 \text{ V}$ .
- 2. Under any condition, ensure that  $V_{\text{TH+}}$  is at least  $V_{\text{HYS}}$  higher than  $V_{\text{TH-}}$



# 7.6. Switching Characteristics

All typical specs are at VCC = 5V,  $T_A$  = 25°C, Min/Max specs are over recommended operating conditions unless otherwise specified.

	Parameters	Test Conditions	Min	Тур	Max	Unit
Driver						
t <sub>r</sub> , t <sub>f</sub>	Driver differential output rise/fall time	$R_1$ =54 Ω, $C_1$ =50pF, Figure 8-3	1	3	6	ns
t <sub>PHL</sub> ,t <sub>PLH</sub>	Propagation delay	- κ <sub>L</sub> -54 Ω, C <sub>L</sub> -50με, Figure 6-5	3	10	20	ns
t <sub>SK(P)</sub>	Pulse skew,  t <sub>PHL</sub> - t <sub>PLH</sub>				3.5	ns
Receiver						
t <sub>r</sub> , t <sub>f</sub>	Output rise/fall time			2	6	ns
t <sub>PHL</sub> ,t <sub>PLH</sub>	Propagation delay	C <sub>L</sub> =15pF, see Figure 8-4		25	40	ns
t <sub>SK(P)</sub>	Pulse skew,  t <sub>PHL</sub> - t <sub>PLH</sub>				3.5	ns

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# 7.7. Typical Characteristics

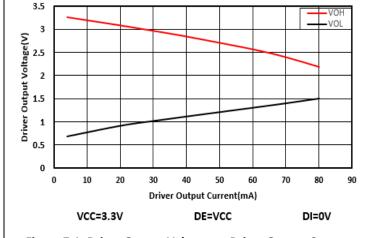


Figure 7-1. Driver Output Voltage vs. Driver Output Current

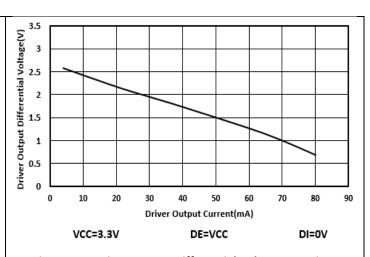


Figure 7-2. Driver Output Differential Voltage vs. Driver Output Current

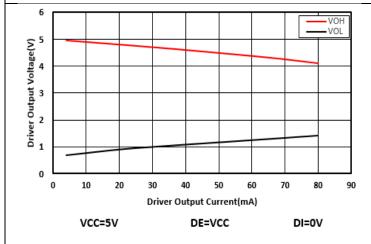


Figure 7-3. Driver Output Voltage vs. Driver Output Current

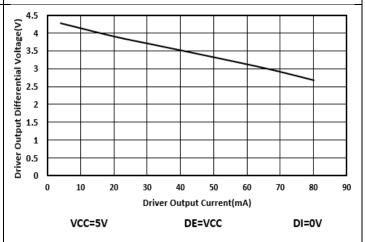
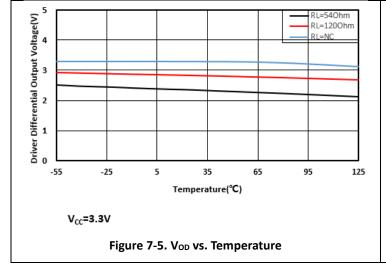
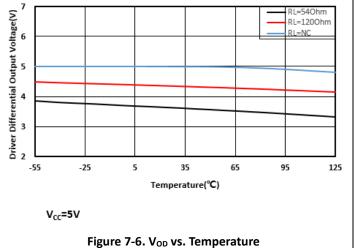


Figure 7-4. Driver Output Differential Voltage vs. Driver Output Current







# **Typical Characteristics (continued)**

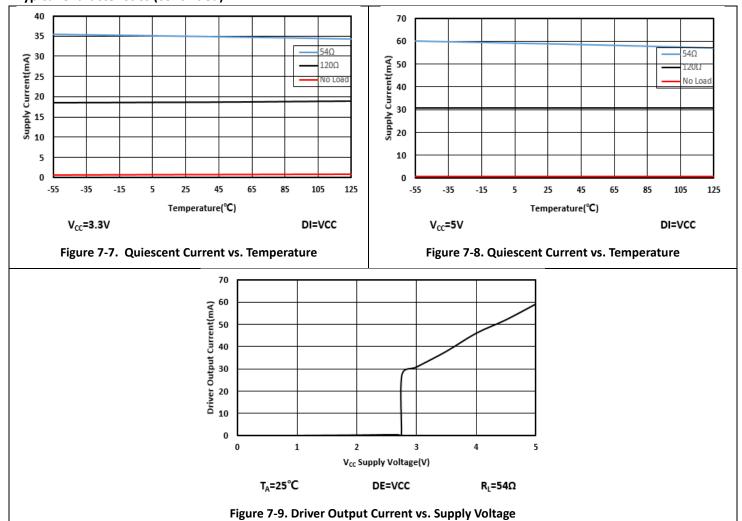
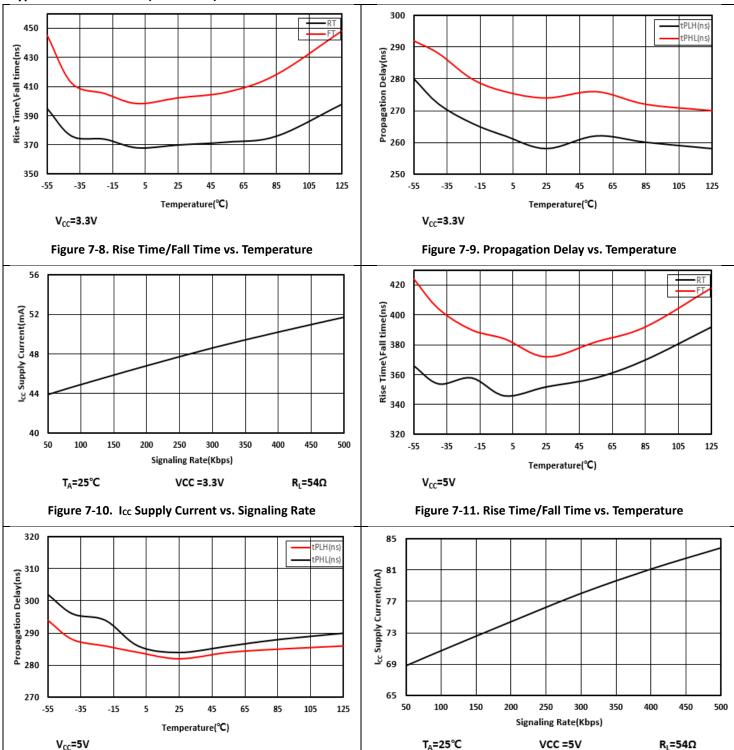


Figure 7-13. Icc Supply Current vs. Signaling Rate

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# **Typical Characteristics (continued)**

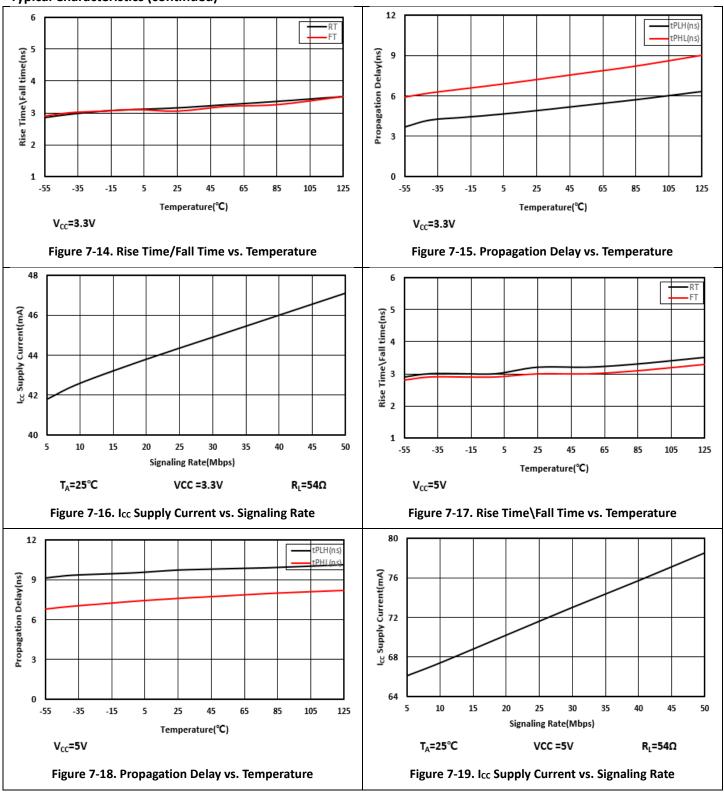
Figure 7-12. Propagation Delay vs. Temperature





# **Typical Characteristics (continued)**

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# 8. Parameter Measurement Information

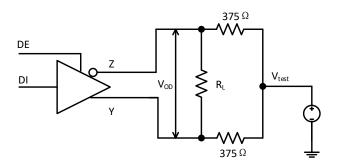


Figure 8-1. Driver Differential Output Voltage with Common-Mode Load

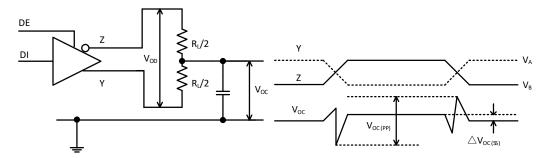


Figure 8-2. Driver Differential and Common-Mode Output with RS-485 Load

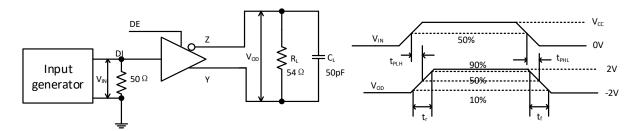


Figure 8-3. Driver Differential Output Rise and Fall Times and Propagation Delays

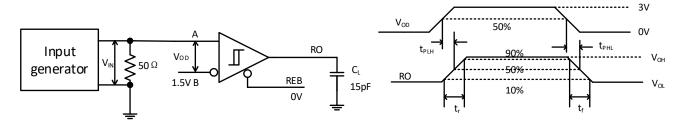


Figure 8-4. Receiver Output Rise and Fall Times and Propagation Delays



## 9. Detailed Description

#### 9.1. Overview

The CA-IF4220NF device is optimized for full-duplex RS-485/RS-422 applications per the EIA/TIA-485 standard. This device contains one differential driver and one differential receiver. The receiver features a 1/8-unit load input impedance, allowing up to 256 transceivers on a single bus. Driver-enable (DE) and receiver-enable (REB) pins are included on the CA-IF4220NF transceivers. When disabled, the driver and receiver outputs are high impedance.

To reduce system complexity and the need for external protection, the driver outputs/receiver inputs of the CA-IF4220NF device are designed to withstand voltage faults of up to ±30V with respect to ground without damage, and the common-mode range exceeds the standard with ±15V for both the driver and receiver. This device also incorporates a high ESD protection circuit capable of protecting against up to ±15kV of ESD Human Body Model (HBM) for driver outputs and receiver inputs. In addition, two mechanisms against excessive power dissipation caused by faults or bus contention. The first, over-current protection on the output stage, provides immediate protection against short circuits over the entire common-mode voltage range. The second, a thermal shutdown circuit, forces the driver outputs into a high-impedance state once the junction temperature of the device exceed the thermal shutdown threshold T<sub>SD</sub> (180°C, typ.). The shutdown condition is cleared when the junction temperature drops to normal operation temperature range of the device.

## 9.2. Device Functional Modes

For the CA-IF4220NF full-duplex device, the driver accepts a single-ended, logic-level input (DI) and transfers it to a differential RS-485/RS-422 level output on the Y and Z bus lines. Set the driver enable input (DE) low to disable the driver. Y and Z are high impedance when the driver is disabled. Also, the DE pin has internal pull-down to GND, when left open, the driver is disabled as well. The DI pin has an internal pull-up resistor to  $V_{CC}$ , thus, when DI left open or a logic high at DI causes Y to turn high and Z to turn low. When DI is low, the output states reverse, Z turns high, Y becomes low. See Table 9-1 for more details.

Input	Enable	Output		Function
DI	DE	Υ	Z	Function
Н	Н	Н	L	Drive bus high
L	Н	L H Di		Drive bus low
Χ	L	Z	Z	Driver disabled
Χ	OPEN	Z	Z	Driver disabled by default
OPEN	Н	Н	L	Drive bus high by default
Note:				
L = Low level; H = Hig	gh level; Z = high impeda	nce; X = Don't care.		

Table 9-1. CA-IF4220NF Driver Function Table

The receiver accepts a differential, RS-485/RS-422 level input on the A and B inputs and transfers it to a single-ended, logic-level output (RO). Drive the receiver enable input (REB) low to enable the receiver. Drive REB high to disable the receiver. RO is high impedance when REB is high. Also, the REB pin has an internal pull-up resistor to  $V_{CC}$ , thus, when left open, the receiver is disabled, and RO output is high impedance.

The CA-IF4220NF includes a true fail-safe feature that ensures the receiver output (RO) is high when the receiver inputs are shorted or open, or when they are connected to a differentially terminated transmission line with all drivers disabled. If the differential receiver input voltage ( $V_A - V_B$ ) is greater than or equal to  $V_{TH+}$  (-20mV, maximum), RO is logic high. When the input voltage ( $V_A - V_B$ ) is less than the negative input threshold  $V_{TH-}$  (-200mV, minimum), the receiver output RO turns low. See Table 9-2 for more details.

Table 0.3	CA-IE4220NE	Danairea	F at: a	Table
Ianie 4-7	$(\Delta - I + \Delta J J I) I I I I I$	ROCOIVOR	FIINCTION	IDNIA

Differential Input	Enable	Output	Function
$V_{ID} = V_A - V_B$	REB	RO	FullCtion
$V_{TH+} < V_{ID}$	L	Н	High-level bus state
$V_{TH-} < V_{ID} < V_{TH+}$	L	Indeterminate	Indeterminate bus state
$V_{ID} < V_{TH}$	L	L	Low-level bus state
X	Н	Z	Receiver disabled
X	OPEN	Z	Receiver disabled by default
Open-circuit bus	L	Н	Fail-safe high output
Short-circuit bus	L	Н	Fail-safe high output
Idle (terminated) bus	L	Н	Fail-safe high output
Note:	•		
L = Low level; H = High level; Z = high impedance.			

# 10. Application Information

The CA-IF4220NF full-duplex RS-485 transceivers commonly used for asynchronous data transmissions. A full-duplex network implementation requires two signal pairs (four wires) cable and allows each node to transmit data on one pair while simultaneously receiving data on the other pair, see Figure 错误!未找到引用源。 a typical point to point application circuit for CA-IF4220NF.

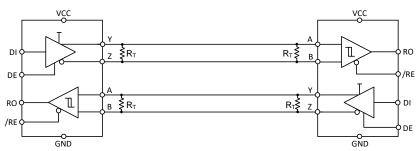
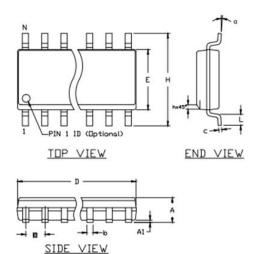


Figure 10-1. Typical Full-duplex Point to Point Operating Circuit



# 11. Package Information

# **SOIC14 Package Outline**



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		COMMO	N DIME	NSIONS	3		
SYMBOL		INCHES		ММ			
SIMBUU	MIN.	TYP.™	MAX.	MIN.	TYP.™	MAX.	
Α	.053	.061	.069	1.35	1.55	1.75	
A1	.004	.007	.010	0.10	0.18	0.25	
b c	.014	.017	.019	0.35	0.42	0.49	
	.007	.009	.010	0.19	0.22	0.25	
E	.150	.154	.157	3.80	3.90	4.00	
е		050 BSC		1.27 BSC			
Н	.228	.236	.244	5.80	6.00	6.20	
L	.016	.033	.050	0.40	0.84	1.27	
α	0*	4*	8*	0*	4*	8.	
h	0.01	0.015	0.019	0.25	0.38	0.5	

\* Typical value provided for reference only. This is not a specification.

	VARIATION A							
SYMBOL	INC	HES		MM				
	MIN.	TYP.*	MAX.	MIN.	TYP. <b>≖</b>	MAX.		
D	.189	.193	.197	4.80	4.90	5.00		
N			8					
MS012	AA							
PKG. CODE	S8+8F, S8+20,	\$8+2C, \$1 \$8+10F, \$8+21, \$ \$8+23,	S8+11F, 8MK+1, S	\$8+16F, 8M+5, \$	SS+2M8	\$8+7F,		

		V	ARIATI	IN B					
SYMBOL	INC	HES		ММ					
	MIN.	TYP. <sup>™</sup>	MAX.	MIN.	TYP. <sup>™</sup>	MAX.			
D	.337	.341	.344	8.55	8.65	8.75			
N			1	4					
MS012	AB								
PKG. CODE		S14+1C 4, S14M			5, S14+6 14M+7	·,			

		V	ARIATI	IN C						
SYMBOL	INC	HES		ММ						
	MIN.	TYP.™	MAX.	MIN.	TYP.™	MAX.				
D	.386	.390	.394	9.80	9.90	10.00				
N	16									
MS012	AC									
PKG. CDDE	\$16+7		9F, S16		5, S16+6 16M+3,					

## NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS DTHERWISE SPECIFIED.
- 2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC # 10-0131.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.15 MM (.006') PER SIDE.
- 4. LEADS TO BE COPLANAR WITHIN 0.10mm (.004").
- 5. MEETS JEDEC MS012
- 6. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PHEREE (+) PKG. CODES.

# 12. Soldering Temperature (reflow) Profile

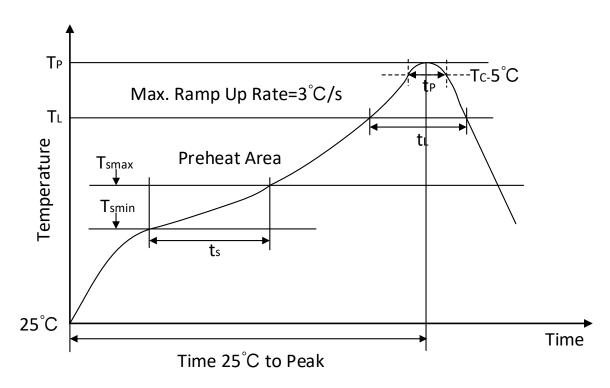


Figure 12-1. Soldering Temperature (reflow) Profile

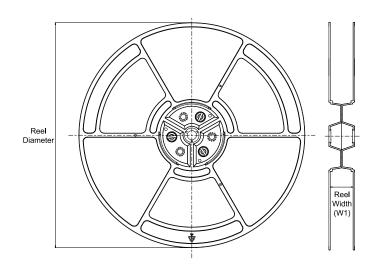
**Table 12-1. Soldering Temperature Parameter** 

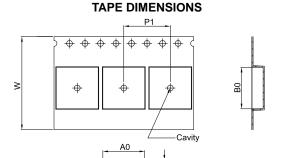
Profile Feature	Pb-Free Assembly
Average ramp-up rate (T <sub>L</sub> =217°C to peak T <sub>P</sub> )	3°C/s max
Time of preheat temperature, 150°C to 200°C	60-120s
Time to be maintained above 217°C	60-150s
Peak temperature	260°C
Time within 5°C of actual peak temperature	30s max
Ramp-down rate (peak T <sub>P</sub> to T <sub>L</sub> =217°C)	6°C/s max
Time from 25 ℃ to peak temperature	8min max



# 13. Tape and Reel Information

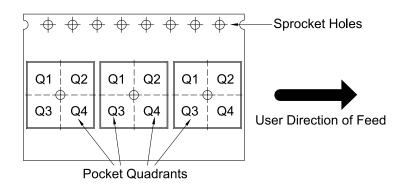
# **REEL DIMENSIONS**





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

# **QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CA-IF4220NF	SOIC	NF	14	2500	330	16.4	6.5	9.0	2.1	8.0	16.0	01

## 14. Important Statement

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